	OCTAL BUFFER AND LINE/MOS DRIVER WITH 3-STATE OUTPUTS SCBS035D – SEPTEMBER 1988 – REVISED MARCH 2003
• Operating Voltage Range of 4.5 V to 5.5 V	DW, N OR NS PACKAGE (TOP VIEW)
<ul> <li>State-of-the-Art BiCMOS Design Significantly Reduces I<sub>CCZ</sub></li> </ul>	
<ul> <li>Output Ports Have Equivalent 33-Ω Series Resistors, So No External Resistors Are</li> </ul>	1A1 2 19 20E 2Y4 3 18 171
Required	1A2 <b>4</b> 17 <b>2</b> A4
3-State Outputs Drive Bus Lines or Buffer	2Y3 [] <sup>5</sup> 16]] 1Y2
Memory Address Registers <ul> <li>ESD Protection Exceeds JESD 22</li> </ul>	1A3 [] 6 15 [] 2A3 2Y2 [] 7 14 [] 1Y3
<ul> <li>2000-V Human-Body Model (A114-A)</li> </ul>	1A4 <mark>]</mark> 8 13 2A2
description/ordering information	2Y1 9 12 1Y4 GND 10 11 2A1

This SN74BCT2241 is designed specifically to

improve both the performance and density of

3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Together with the 'BCT2240 and 'BCT2244 devices, this device provides the choice of selected combinations of inverting and noninverting outputs, symmetrical active-low output-enable (OE) inputs, and complementary OE and OE inputs. This device features high fan-out and improved fan-in.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to V<sub>CC</sub> through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

The outputs, which are designed to source or sink up to 12 mA, include 33-Ω series resistors to reduce overshoot and undershoot.

TA	PACKAGE <sup>†</sup>		PACKAGET		PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74BCT2241N	SN74BCT2241N				
0°C to 70°C	SOIC - DW	Tube	SN74BCT2241DW	BCT2241				
	30IC - DW	Tape and reel	SN74BCT2241DWR	BC12241				
	SOP – NS	Tape and reel	SN74BCT2241NSR	BCT2241				

## **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLES						
INPUTS		OUTPUT				
1 <mark>0E</mark>	1A	1Y				
L	Н	Н				
L	L	L				
н	Х	Z				

INPUTS		OUTPUT
20E	2A	2Y
н	Н	Н
н	L	L
L	Х	Z



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

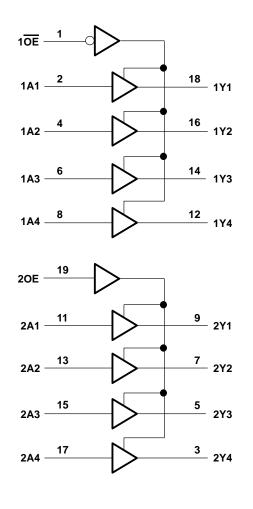


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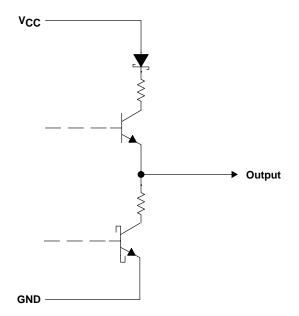
SN74BCT2241

## SN74BCT2241 OCTAL BUFFER AND LINE/MOS DRIVER WITH 3-STATE OUTPUTS SCBS035D – SEPTEMBER 1988 – REVISED MARCH 2003

logic diagram (positive logic)



## schematic of Y outputs





## SN74BCT2241 OCTAL BUFFER AND LINE/MOS DRIVER WITH 3-STATE OUTPUTS

SCBS035D - SEPTEMBER 1988 - REVISED MARCH 2003

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

$ \begin{array}{llllllllllllllllllllllllllllllllllll$	7 V .5 V VCC mA mA C/W C/W C/W
Storage temperature range, T <sub>stg</sub>	0°C

<sup>+</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 3)

		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			0.8	V
Iк	Input clamp current			-18	mA
IОН	High-level output current			-12	mA
IOL	Low-level output current			12	mA
TA	Operating free-air temperature	0		70	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



# SN74BCT2241 **OCTAL BUFFER AND LINE/MOS DRIVER** WITH 3-STATE OUTPUTS

SCBS035D - SEPTEMBER 1988 - REVISED MARCH 2003

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	түр†	MAX	UNIT
VIK	V <sub>CC</sub> = 4.5 V,	lı = -18 mA			-1.2	V
		$I_{OH} = -1 \text{ mA}$	2.4	3.3		
VOH	$V_{CC} = 4.5 V$	$I_{OH} = -12 \text{ mA}$	2			V
	V <sub>CC</sub> = 4.75 V,	$I_{OH} = -3 \text{ mA}$	2.7			
Max		I <sub>OL</sub> = 1 mA		0.15	0.5	V
VOL	$V_{CC} = 4.5 V$	I <sub>OL</sub> = 12 mA		0.42	0.8	v
lj	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 7 V			0.1	mA
Ιн	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20	μA
۱ <sub>IL</sub>	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.5 V			-1	mA
IOZH	V <sub>CC</sub> = 5.5 V,	$V_{O} = 2.7 V$			50	μΑ
I <sub>OZL</sub>	V <sub>CC</sub> = 5.5 V,	$V_{O} = 0.5 V$			-50	μA
los‡	V <sub>CC</sub> = 5.5 V,	$V_{O} = 0$	-100		-225	mA
ІССН	V <sub>CC</sub> = 5.5 V,	Outputs open		23	37	mA
ICCL	V <sub>CC</sub> = 5.5 V,	Outputs open		48	76	mA
ICCZ	V <sub>CC</sub> = 5.5 V,	Outputs open		6	9	mA
Ci	V <sub>CC</sub> = 5 V,	V <sub>I</sub> = 2.5 V or 0.5 V		6		pF
Co	V <sub>CC</sub> = 5 V,	$V_{O} = 2.5 \text{ V or } 0.5 \text{ V}$		11		pF

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>‡</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

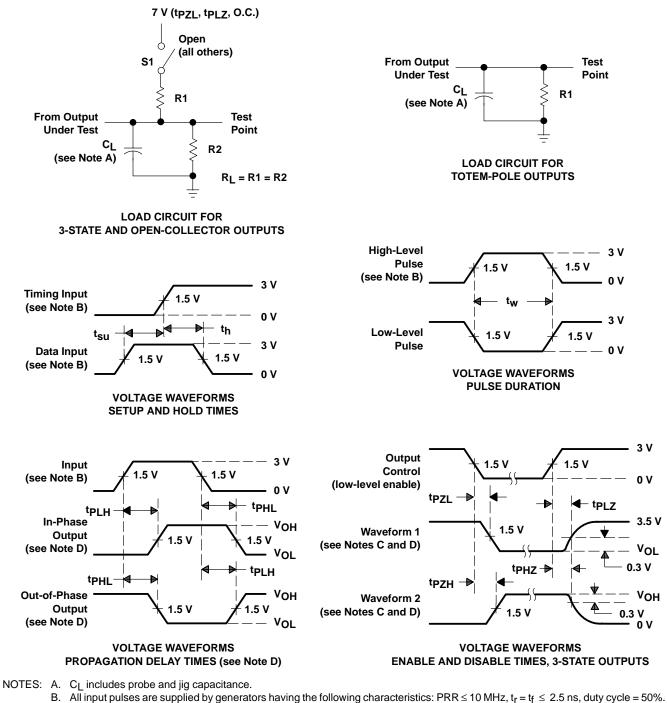
PARAMETER	FROM (INPUT)	то (оитрит)	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			MIN	МАХ	UNIT
			MIN	TYP	MAX			
<sup>t</sup> PLH	A	V	1.1	3	4.4	1.1	4.9	20
<sup>t</sup> PHL		T	2.9	4.9	6.6	2.9	6.9	ns
<sup>t</sup> PZH		V	2.7	6	7.8	2.7	8.9	20
<sup>t</sup> PZL		T	4.1	7.7	9.4	4.1	10.3	ns
<sup>t</sup> PHZ	OE or OE	v	2.5	5.2	7.2	2.5	8.7	
<sup>t</sup> PLZ		Ĭ	3.2	7.1	9.5	3.2	11.3	ns



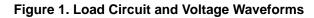
# SN74BCT2241 **OCTAL BUFFER AND LINE/MOS DRIVER** WITH 3-STATE OUTPUTS

SCBS035D - SEPTEMBER 1988 - REVISED MARCH 2003

### PARAMETER MEASUREMENT INFORMATION



- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.
- E. When measuring propagation delay times of 3-state outputs, switch S1 is open.
- F. All parameters and waveforms are not applicable to all devices.



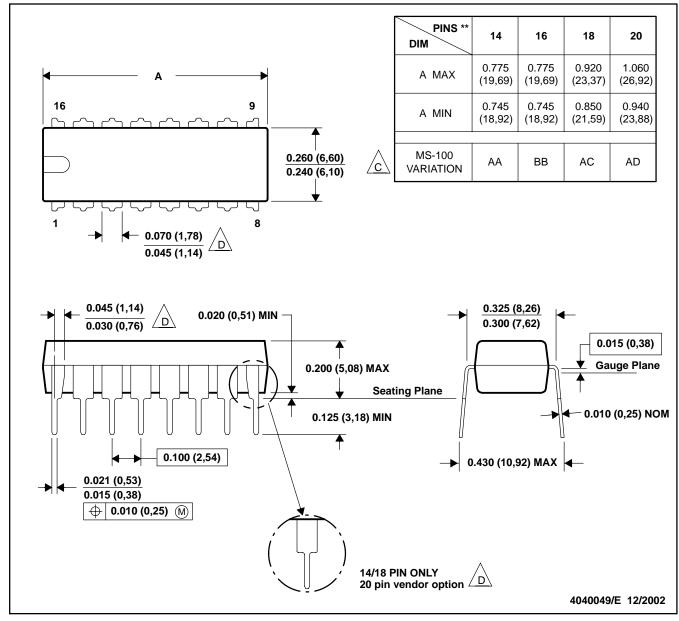


MPDI002C - JANUARY 1995 - REVISED DECEMBER 20002

### N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

/д.

B. This drawing is subject to change without notice.

/C Falls within JEDEC MS-001, except 18 and 20 pin minimum body Irngth (Dim A).

The 20 pin end lead shoulder width is a vendor option, either half or full width.

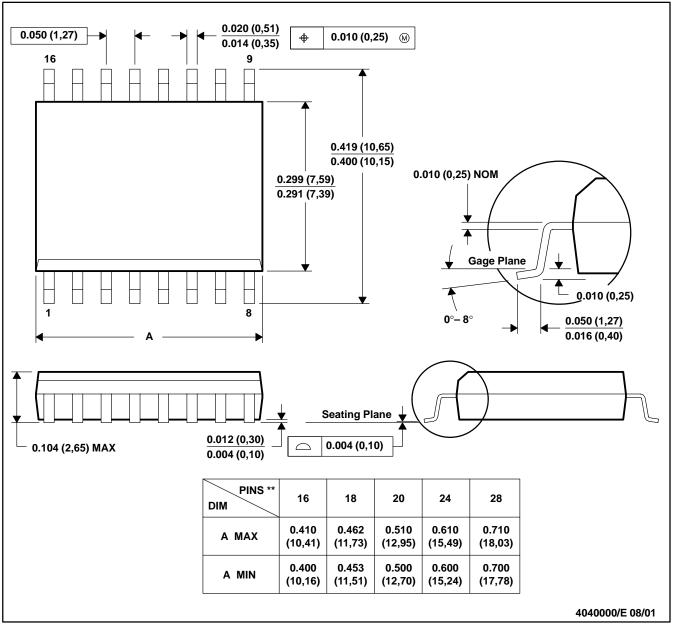


# **MECHANICAL DATA**

MSOI003E - JANUARY 1995 - REVISED SEPTEMBER 2001

### PLASTIC SMALL-OUTLINE PACKAGE

DW (R-PDSO-G\*\*) 16 PINS SHOWN



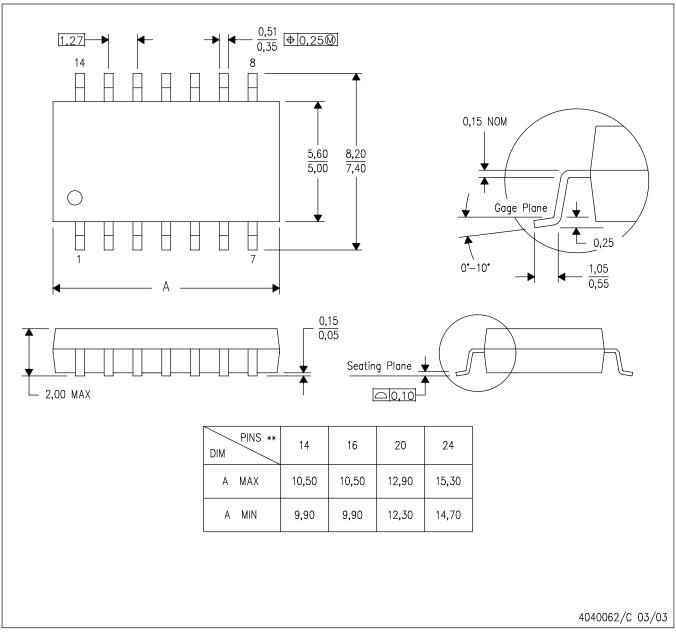
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013



NS (R-PDSO-G\*\*) 14-PIN SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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